

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT	
<b>CONVEYING PARTY DATA</b>		
	<b>Name</b>	<b>Execution Date</b>
	YONG SOO CHO	12/14/2015
<b>RECEIVING PARTY DATA</b>		
<b>Name:</b>	DONGBU HITEK CO., LTD.	
<b>Street Address:</b>	432, TEHERAN-RO	
<b>Internal Address:</b>	GANGNAM-GU	
<b>City:</b>	SEOUL	
<b>State/Country:</b>	KOREA, REPUBLIC OF	
<b>Postal Code:</b>	06194	
<b>PROPERTY NUMBERS Total: 1</b>		
	<b>Property Type</b>	<b>Number</b>
	Application Number:	15041594
<b>CORRESPONDENCE DATA</b>		
<b>Fax Number:</b>	(612)349-9266	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
<b>Phone:</b>	612-349-5740	
<b>Email:</b>	arcand@ptslaw.com	
<b>Correspondent Name:</b>	BRAD PEDERSEN	
<b>Address Line 1:</b>	80 SOUTH EIGHTH STREET	
<b>Address Line 2:</b>	4800 IDS CENTER	
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402	
<b>ATTORNEY DOCKET NUMBER:</b>	4785.16US01	
<b>NAME OF SUBMITTER:</b>	MICHELLE ARCAND	
<b>SIGNATURE:</b>	/Michelle Arcand/	
<b>DATE SIGNED:</b>	02/19/2016	
<b>Total Attachments: 2</b>		
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ASSIGNMENT

WHEREAS, I, Yong Soo CHO, of Daejeon, Republic of Korea ("Assignor"), have invented certain new and useful improvements in SEMICONDUCTOR DEVICE AND RADIO FREQUENCY MODULE FORMED ON HIGH RESISTIVITY SUBSTRATE, for which an application for Letters Patent of the United States is being made, and which may be identified in the United States Patent Office by Application No. 15/041,594, filed February 11, 2016.

WHEREAS, Dongbu Hitek Co., Ltd. ("Assignee"), a business entity organized and existing under the laws of the Country of Republic of Korea, and having its principal offices at 432, Teheran-ro, Gangnam-gu Seoul, 06194 Republic of Korea, is desirous of acquiring the entire right, title and interest in and to said invention, said application and in, to and under any and all Letters Patent to be obtained therefor;

NOW, THEREFORE, for and in consideration of good and valuable consideration paid by Assignee to Assignor, the receipt and sufficiency of which is hereby acknowledged by me, I have sold, assigned and transferred, and by these presents do hereby sell, assign and transfer unto the said Assignee, its successors and assigns, my entire right, title and interest in and to said invention, said application, all applications claiming priority to said application including all divisions, continuations or renewals thereof, and the Letters Patent, both foreign and domestic, that may or shall issue, therefrom including all reissues or extensions of such patents including all of my rights under the International Convention and further including the right to sue, counterclaim and recover for past, present and future infringement of the rights assigned or to be assigned, as fully and entirely as the same would have been held by the Assignor if this assignment had not been made, and I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to the above mentioned Assignee in accordance herewith.

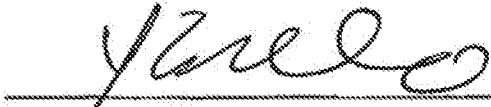
I hereby authorize the above-mentioned Assignee, its successors and assigns, or anyone it may properly designate, to insert in this instrument the date of execution and/or filing date and application number of said application when ascertained.

I further authorize said Assignee, its successors and assigns, or anyone it may properly designate, to apply for Letters Patent, in its own name if desired, in any and all foreign countries, and additionally to claim the filing date of said United States application and/or otherwise take advantage of the provisions of the International Convention.

Upon said consideration I do hereby covenant and agree with the said Assignee, its successors and assigns, that I will not execute in writing or do any act whatsoever conflicting with these presents, and that I or my executors or administrators will at any time upon request, without further or additional consideration, but at the expense of the said Assignee, its successors and assigns, execute such additional writings and do such additional acts as said Assignee, its successors and assigns, may deem necessary or desirable to perfect the Assignee's enjoyment of this grant, and render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, or of any and all foreign countries on said invention, and in enforcing any rights occurring as a result of such applications

or patents, by giving testimony in any proceedings or transactions involving such applications or patents.

Date: 14/12/2015  
Day/Month/Year

  
Yong Soo CHO